Doc Code: AP.PRE.REQ

★Total of ...

PTO/SB/33 (07-05)

Approved for use through xx/xx/200x. OMB 0651-00xx

U.S. Patent and Trademark Office; US DEPARTMENT OF COMMERCE

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it displays a valid OMB control number

PRE-APPEAL BRIEF REQUEST FOR REVIEW		Docket	Docket Number (Optional)	
		SC119	SC11931TP	
Certificate of Transmission under 37 CFR 1.8	Application Nun	nber	Filed	
I hereby certify that this correspondence is being facsimile transmitted orX e-filed to the United States Patent and Trademark Office - Mail Stop AF.	10/075218		02-14-2002	
	First Named Inventor			
on <u>March 28, 2008</u>	KOBAYASHI, THOMAS			
			Examiner	
Signature /Dee Matocha/	***			
Typed or printed name: Dee Matocha	2891		STEVEN J. FULK	
filed with this request. This request is being filed with a notice of appeal.				
The review is requested for the reason(s) stated on the attached sheet(s). Note: No more than five (5) pages may be provided. I am the				
applicant/inventor.				
		im-Marie Vo/	Signature	
assignee of record of the entire interest.			•	
See 37 CFR 3.71. Statement under 37 CFR 3.73(b) is enclosed.			VO, KIM-MARIE	
(Form PTO/SB/96) Typed or printed name				
			(512) 996-6839	
			Telephone number	
attorney or agent acting under 37 CFR 1.34 Registration number if acting under 37 CFR 1.34				
			Date	
NOTE: Signatures of all the inventors or assignees of record of the entire interest or their representative(s) are required. Submit multiple forms if more than one signature is required, see below*.				

The collection of information is required by 35 U.S.C. 132. The information is required to obtain of retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality if governed by 35 U.S.C. 122 and 37 CFR 1.11, 1.14 and 41.6. This collection is estimated to take 12 minutes to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Mail Stop AF, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

forms are submitted

REMARKS

Claims 1-7, 9, 11-18, 20 and 21 are pending.

Claim Rejections

Claims 1, 2, 9, 11, 12, 17, 18, 20, and 21 are patentable under 35 U.S.C. 103(a) over Kono (U.S. 5,972,756) in view of Weber (U.S. 6,218,279).

Applicants submit Kono fails to teach at least [forming] a fuse overlying a passivation layer, as stated in independent claims 1, 11 and 18 from which all other pending claims depend. In contrast to the Examiner's position, Applicants submit Kono teaches a fuse under a passivation layer. The disagreement revolves around whether an inter-layer (e.g., Kono's layer 124) is a passivation layer.

Applicants Position:

Applicant submits an inter-layer (including Kono's layer 124) is not a passivation layer. Kono states, "Reference numeral 124 denotes an inter-layer insulating film of a TEOS oxide film simultaneously formed on the entire surface of the inter-layer insulating film 120." and "Reference numeral 150 denotes a passivation film of a silicon nitride film (Si.sub.3 N.sub.4) ..." (See 4th and 7th paragraphs under Description of the Preferred Embodiments section.) First, Kono distinguishes passivation 150 and non-passivation 124 layers by using different terms. If layer 124 was a passivation layer, Kono would have said so. Second, Kono's passivation layer 150 serves a different purpose than Kono's inter-layer insulating film 124 and based on Applicants specification and the meaning of the phrase "passivation layer" to one skilled in the art, Kono's interlayer is not a passivation layer.

Examiner's Positions and Applicants Rebuttals:

- 1. First, the Examiner contends Kono's inter-layer 124 meets Applicants' description (in the specification) of a passivation layer. On page 6, lines 18-22 of the specification, "The passivation layer 35 is formed over the ILD layer 20 and the conductive regions 30 to protect eth underlying layers from physical handling of the semiconductor device 5 the environment (especially humidity), and t patterned using conventional means to expos portions of the conductive regions 30."
 - a. Applicants submit that Kono's inter-layer 124 does not meet Applicants' description of a passivation layer. Kono's inter-layer 124 does not

"protect the underlying layers from physical handling and from the environment." Instead, Kono's layer 150, which Kono terms a passivation layer, does this. To find that Kono's inter-layer 124 protects underlying layers from physical handling and the environment would mean the phrase "passivation layer" is meaningless because as any layer would qualify as a passivation layer because any layer (except the first layer formed) protects underlying layers from physical handling and the environment.

- b. Furthermore, a skilled artisan understands that the passivation layer is different than an inter-layer (or intermetal dielectric (IMD) layer) because the inter-layer is between conductive layers and the passivation layer formed over conductive layers. Both Applicants specification and Kono use the term passivation layer as one skilled in the art would and distinguish the passivation layers from intermediate layers as one skilled in the art would.
- 2. Second, the Examiner rebuts Applicants arguments that an inter-layer is not a passivation layer by arguing that there can be more than one passivation layer and providing references (Bryant and Udo) that teach multiple passivation layers.
 - a. Applicants agree that there can be more than one passivation layer, as taught by Bryant and Udo. This argument is irrelevant to Applicants' point. Applicants contend that an inter-layer cannot be a passivation layer, no matter how many passivation layers are present. Neither Bryant nor Udo teach or suggest to a skilled artisan that an inter-layer is a passivation layer because the passivation layers in Bryant and Udo are not between conductive layers like an inter-layer. Instead, Bryant and Udo are using the phrase passivation layer as one skilled in the art would: a layer that protects the integrated circuit prior to encapsulation.

In summary, in all the provided references (and Applicants' specification), the phrase "passivation layer refers to layers that are formed over conductive layers, not between conductive layers like a Kono's inter-layer 124. Hence, for at least this reason, the cited prior art fails to teach or suggest to a skilled artisan all features of the claims. For example, the references fail to teach or suggest, "[forming] a fuse overlying a passivation layer." For at least this reason, all of the pending claims are allowable. Hence, Applicants earnestly solicit allowance of all pending claims.

The Office Action contains numerous statements characterizing the claims, the specification, and the prior art. Regardless of whether such statements are addressed by Applicants, Applicants refuse to subscribe to any of these statements, unless expressly indicated by Applicants.